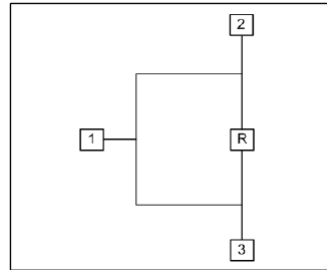


Features

- Frequency: 26-31GHz
- Insertion Loss: 0.3dB
- Input/Output: 50Ω matched
- Die Size: 1.25 x 1.1 x 0.1 mm

Functional Block Diagram

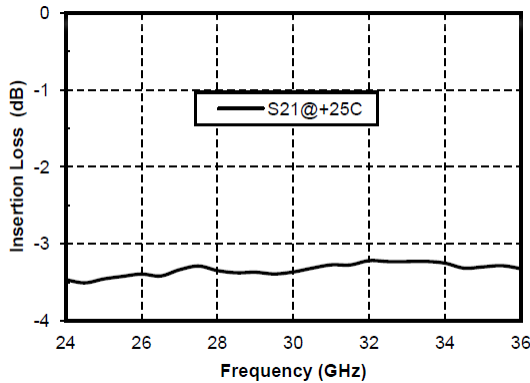


Electrical Specifications

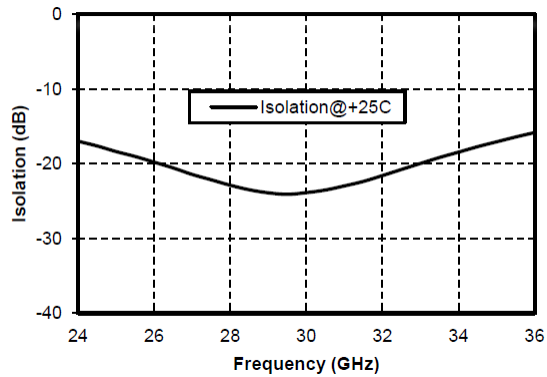
TA = +25°C

Parameters	Min.	Typ.	Max.	Units
Frequency	26-31			GHz
Insertion Loss	0.3	0.3	0.4	dB
Flatness		±0.05		dB
Isolation	20	22		dB
Input Return Loss	13	15		dB
Output Return Loss	18	20		dB

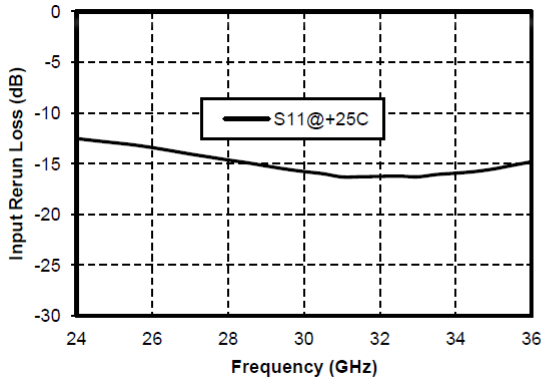
Insertion Loss



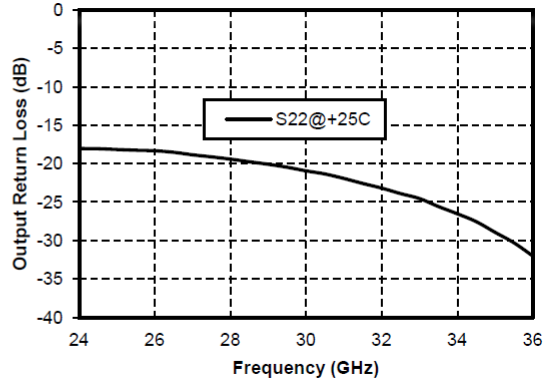
Isolation



Input Return Loss

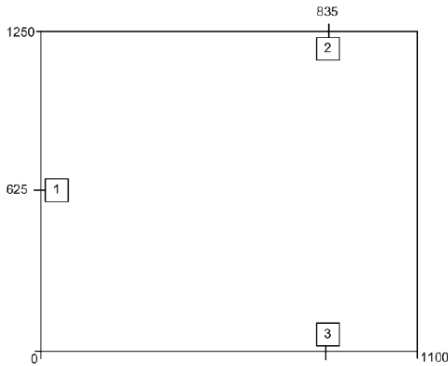


Output Return Loss

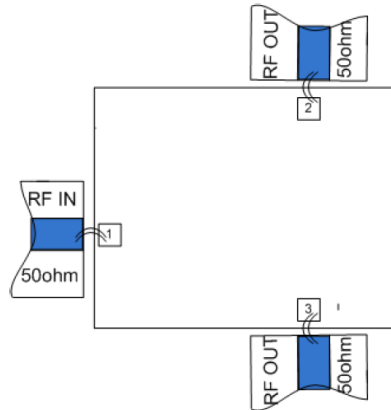


Outline Drawing

All Dimensions in um



Assembly Drawing



Pad Description

Pad	Function	Description
1	RF IN	RF Input Port
2,3	RF OUT	RF Output Port
Die bottom	GND	Die bottom must be connected to RF/DC ground.

Maximum Ratings:

1. Maximum input power: +40dBm
2. Operating temperature: -55°C to +85°C
3. Storage temperature: -65°C to +150°C